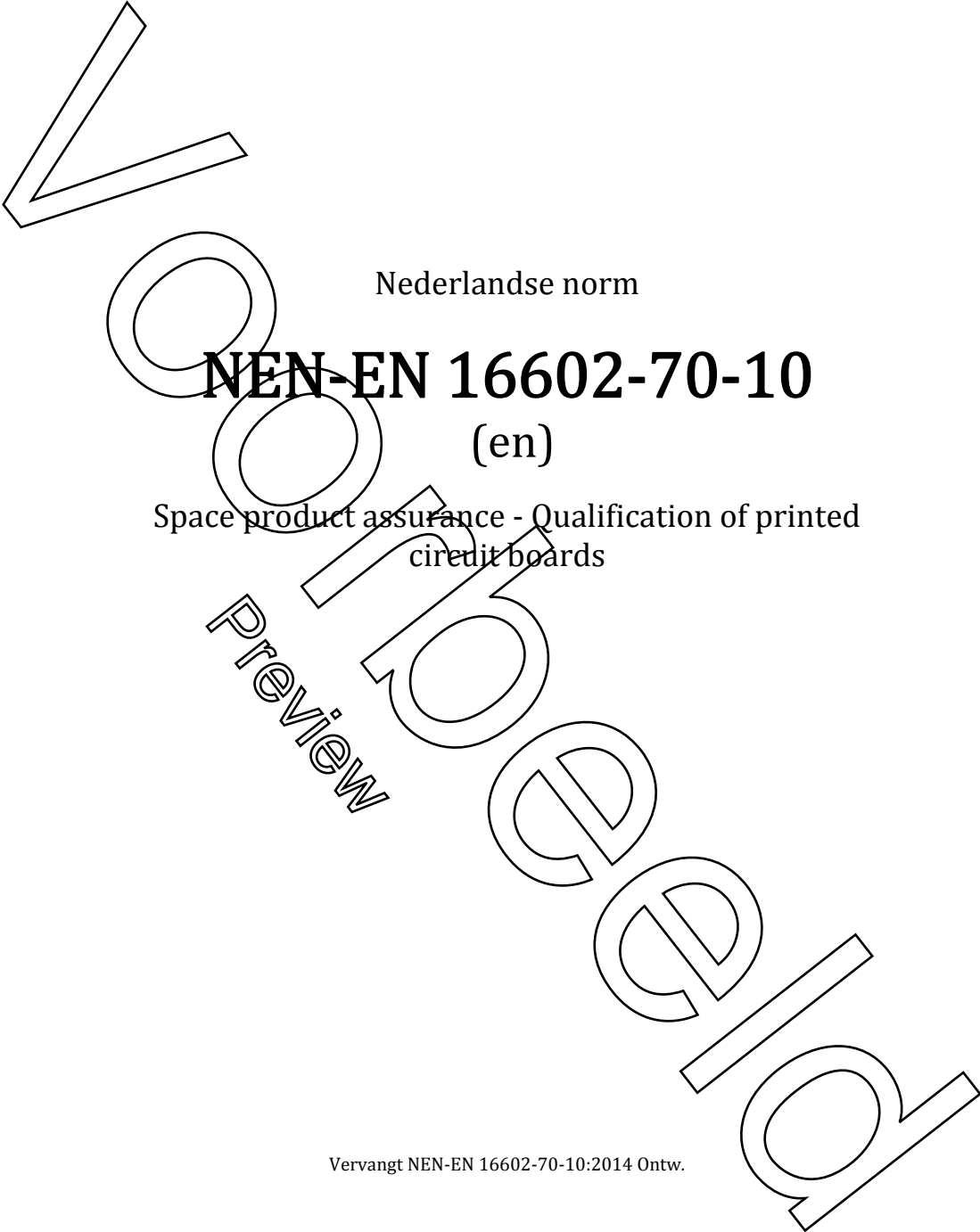


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Nederlandse norm

NEN-EN 16602-70-10

(en)

Space product assurance - Qualification of printed circuit boards

Vervangt NEN-EN 16602-70-10:2014 Ontw.

ICS 31.180; 49.140

februari 2015

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EN 16602-10-09	NEN-EN 16602-10-09	Space product assurance - Nonconformance control system
EN 16602-20	NEN-EN 16602-20	Space product assurance - Quality assurance
EN 16602-70	-	-
EN 16602-70-02	NEN-EN 16602-70-02	Space product assurance - Thermal vacuum outgassing test for the screening of space materials
EN 16602-70-08	NEN-EN 16602-70-08	Space product assurance - Manual soldering of high-reliability electrical connections
EN 16602-70-11	-	-
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EN 16602-70-22	NEN-EN 16602-70-22	Space product assurance - Control of limited shelf-life materials
EN 16602-70-29	-	-
IEC 60068-2-3:1961	-	-
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IEC 60249-1-am 4	-	-
IEC 60326-2-am 1	-	-
IEC 60326-5-am 1	-	-
IEC 60326-8	NEN 10326-8	Prentpanelen - Deel 8: Specificatie voor enkel- en dubbelzijdige flexibele prentpanelen met doorverbindingen
IEC 60326-11	NEN 10326-11	Prentpanelen - Deel 11: Specificatie voor semiflexibele meerlaags prentpanelen met doorverbindingen
IEC 62326-4	NEN 12326-4	Printplaten - Deel 4: Stijve meerlaags printplaten met verbindingen tussen de lagen - Groepsspecificatie

Voorbeeld
Preview

EUROPEAN STANDARD

EN 16602-70-10

NORME EUROPÉENNE

EUROPÄISCHE NORM

January 2015

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English version

Space product assurance - Qualification of printed circuit boardsAssurance produit des projets spatiaux - Qualification des
circuits imprimésRaumfahrtproduktsicherung - Qualifizierung von
Leiterplatten

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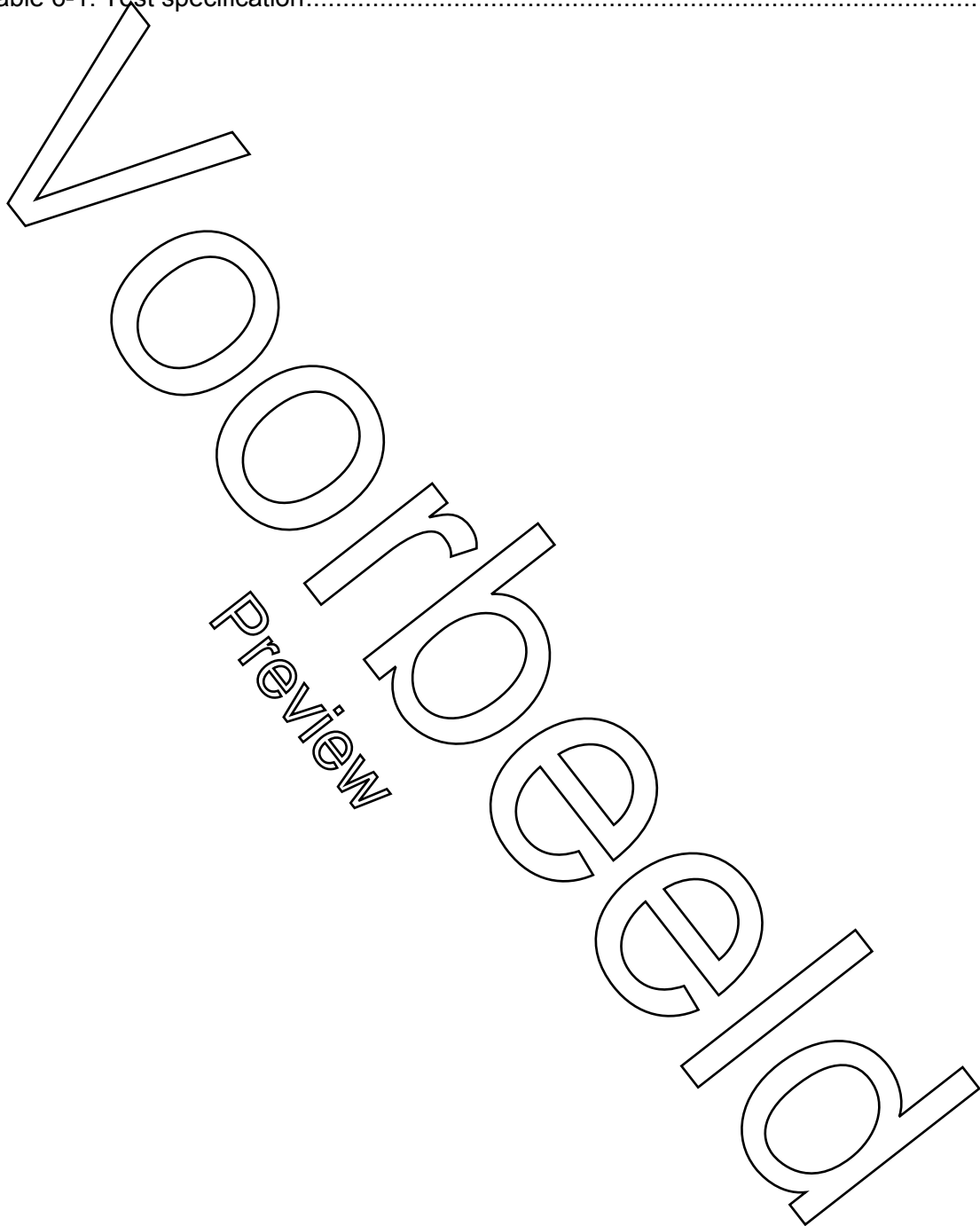
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Foreword

This document (EN 16602-70-10:2015) has been prepared by Technical Committee CEN/CLC/TC 5 "Space", the secretariat of which is held by DIN.

This standard (EN 16602-70-10:2015) originates from ECSS-Q-ST-70-10C.

This European Standard shall be given the status of a national standard, either by publication of an identical text or by endorsement, at the latest by July 2015, and conflicting national standards shall be withdrawn at the latest by July 2015.

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1 Scope

This Standard defines the requirements for evaluation, qualification and maintenance of qualification of PCB manufacturers for different types of PCBs.

This Standard is applicable to the following type of PCBs:

- Rigid PCBs (single-sided, double-sided, multilayer, sequential-laminated multilayer, metal core)
- Flexible PCB (single-sided and double-sided)
- Rigid-flex PCBs (multilayer and sequential-laminated multilayer)
- High frequency PCBs
- Special PCBs.

PCBs are used for the mounting of components in order to produce PCB assemblies performing complex electrical functions. The PCBs are subjected to thermal and mechanical shocks during their assembly such as mounting of components by soldering, rework and repair under normal terrestrial conditions, and in addition the complex PCB assembly are subjected to the environment imposed by launch and space flights.

This standard may be tailored for the specific characteristics and constraints of a space project in conformance with ECSS-S-ST-00.

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